

Call for Papers

The 13th IEEE International 3D Systems Integration Conference 2024 (3DIC2024)

September 25 (Wed.) to 27 (Fri.),

Hotel Metropolitan Sendai and Sendai Kokusai Hotel

<https://3dic-conf.org>

The 13th IEEE International 3D Systems Integration Conference 2024 (3DIC2024) will be held from September 25 (Wed.) to 27 (Fri.), 2024, at Hotel Metropolitan Sendai and Sendai Kokusai Hotel.

This conference is a continuation of the first international conference on 3DIC held in Japan, 3D-SIC2007, in March 2007 under the auspices of the Advanced Science and Engineering Technology Development Organization (ASET). Since 2009, the conference has been held annually in Japan, Europe, and the United States in rotation, sponsored by the IEEE. The research on 3D-IC/Chiplet and system integration requires a wide range of knowledge. Therefore, we will continue to develop and implement 3D-IC/Chiplet and system integration. This conference enables active discussions that transcend specialized areas, encourages dedicated participation by professionals and young researchers, and aims to develop this. The Best Young Researcher or Student Award will be presented on the final day. We believe that many of you will contribute to the conference.

Please submit one page of text (500 words) and one page of figures as an abstract.

The conference invites papers on the following topics (but not limited to)

3D/Chiplet Integration Technology

Through-Si Vias (TSV), Hybrid bonding, Wafer thinning, Wafer/Chip alignment, WtW/WtC/CtC bonding, Wafer dicing, Interposer (Si/Glass/Organic), Optical interconnect, FOWLP Optical interconnect, FOWLP, Monolithic 3D integration, Heterogeneous integration, and Chiplet technology

3D/Chiplet Circuits Technology

SoC, 3D NAND, HBM, CPU/GPU, DSP, FPGA, ASIC, RF and mm-wave, Analog circuits, Biomedical circuits, and Chiplet design

3D/Chiplet Applications

Artificial Intelligence, Quantum Computing, Post 5G/6G, Intelligent Sensor Systems, Bio/Medical Imaging, and VR/AR

3D/Chiplet Design and Test Methodology

CAD, Synthesis, Design flow, Signal and power integrity analysis and design in 3D/Chiplet, Thermal design and analysis, Test and design for test, Mechanical stress and reliability design and analysis, Mechanical stress and reliability design and analysis

The deadline for submission is Friday, June 14, 2024.

For more information, please visit the following URL

<https://3dic-conf.org/2024-call-for-papers/>

Papers presented at 3DIC2024 will be published in IEEE Xplore.

We welcome submissions from students and young researchers.

3DIC2024 CONFERENCE CHAIR

Tetsu Tanaka (Tohoku University)

For inquiries, please contact

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Conference website: <https://3dic-conf.org>